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(12) **United States Design Patent**
Kim et al.

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(45) **Date of Patent:** **** Feb. 23, 2021**

(54) **THREE DIMENSIONAL FACETED IDENTIFICATION CHIP**

(71) Applicant: **Lexmark International, Inc.**,
Lexington, KY (US)

(72) Inventors: **Hyeob Kim**, Independence, KY (US);
Thomas Eugene Pangburn,
Winchester, KY (US); **Scott Richard Castle**,
Lexington, KY (US); **Robert Henry Muyskens**,
Lexington, KY (US); **Brant Dennis Nystrom**,
Lexington, KY (US); **Samuel Leo Rhodus**,
Lexington, KY (US)

(73) Assignee: **LEXMARK INTERNATIONAL, INC.**,
Lexington, KY (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/684,253**

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(51) **LOC (13) Cl.** **14-02**

(52) **U.S. Cl.**
USPC **D14/384**

(58) **Field of Classification Search**

USPC D14/356-358, 383-385, 420, 426, 427,
D14/432-439, 447, 453, 454, 217, 253,
D14/299, 307; D13/107, 108, 133, 146,
D13/147, 152, 154, 156, 158, 162, 162.1,
D13/168, 173, 177, 102; 235/441, 451,
235/492, 380, 439, 375; 361/679.31, 600,
361/679.01, 679.02

CPC G07C 9/00103; G07C 9/00039; G07C
9/00904; G06K 5/00; G06K 7/01

See application file for complete search history.

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Primary Examiner — Austin Murphy

(57) **CLAIM**

The ornamental design for three dimensional faceted identification chip, as shown and described.

DESCRIPTION

FIG. 1 is a front, top, and right side perspective view of a three dimensional faceted identification chip showing our new design;

FIG. 2 is a rear, bottom, and left side perspective thereof;

FIG. 3 is front elevation thereof;

FIG. 4 is a right side elevation thereof;

FIG. 5 is a rear elevation thereof;

FIG. 6 is a left side elevation thereof;

FIG. 7 is a top plan view thereof;

FIG. 8 is a bottom plan view thereof;

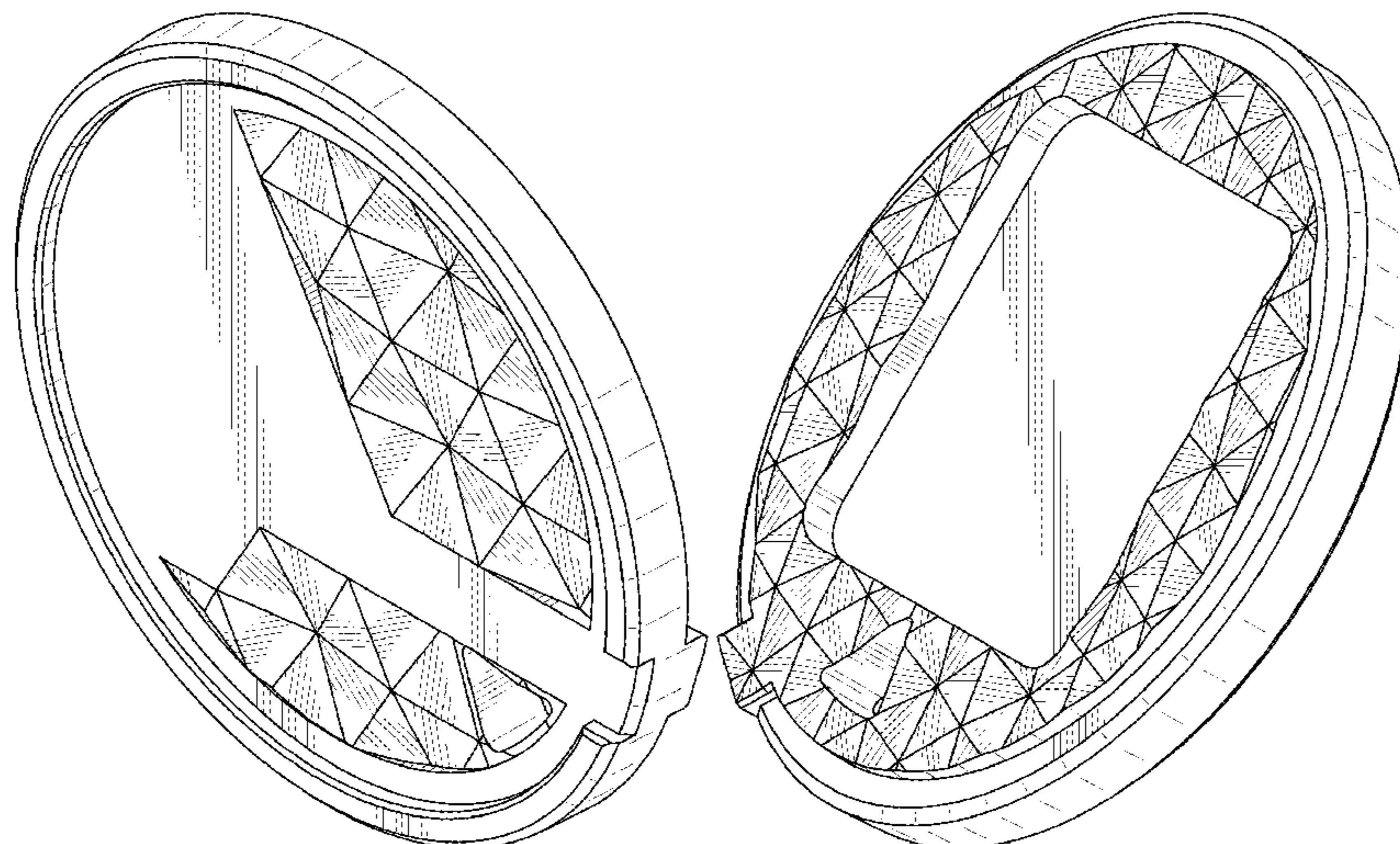
FIG. 9 is a section view thereof, as identified in FIG. 3;

FIG. 10 is a section view thereof, as identified in FIG. 3; and,

FIG. 11 is a section view thereof, as identified in FIG. 3.

The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



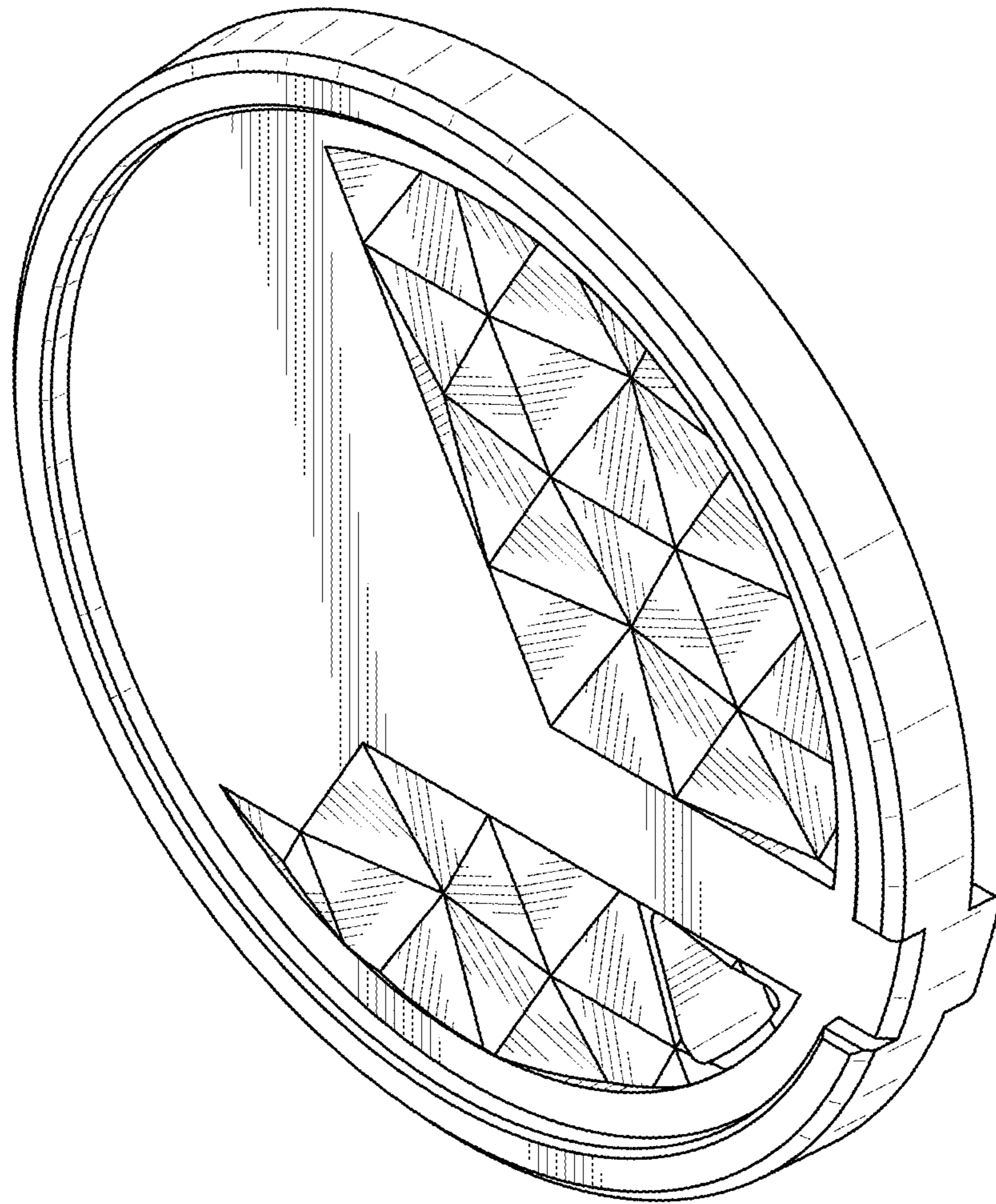


FIG. 1

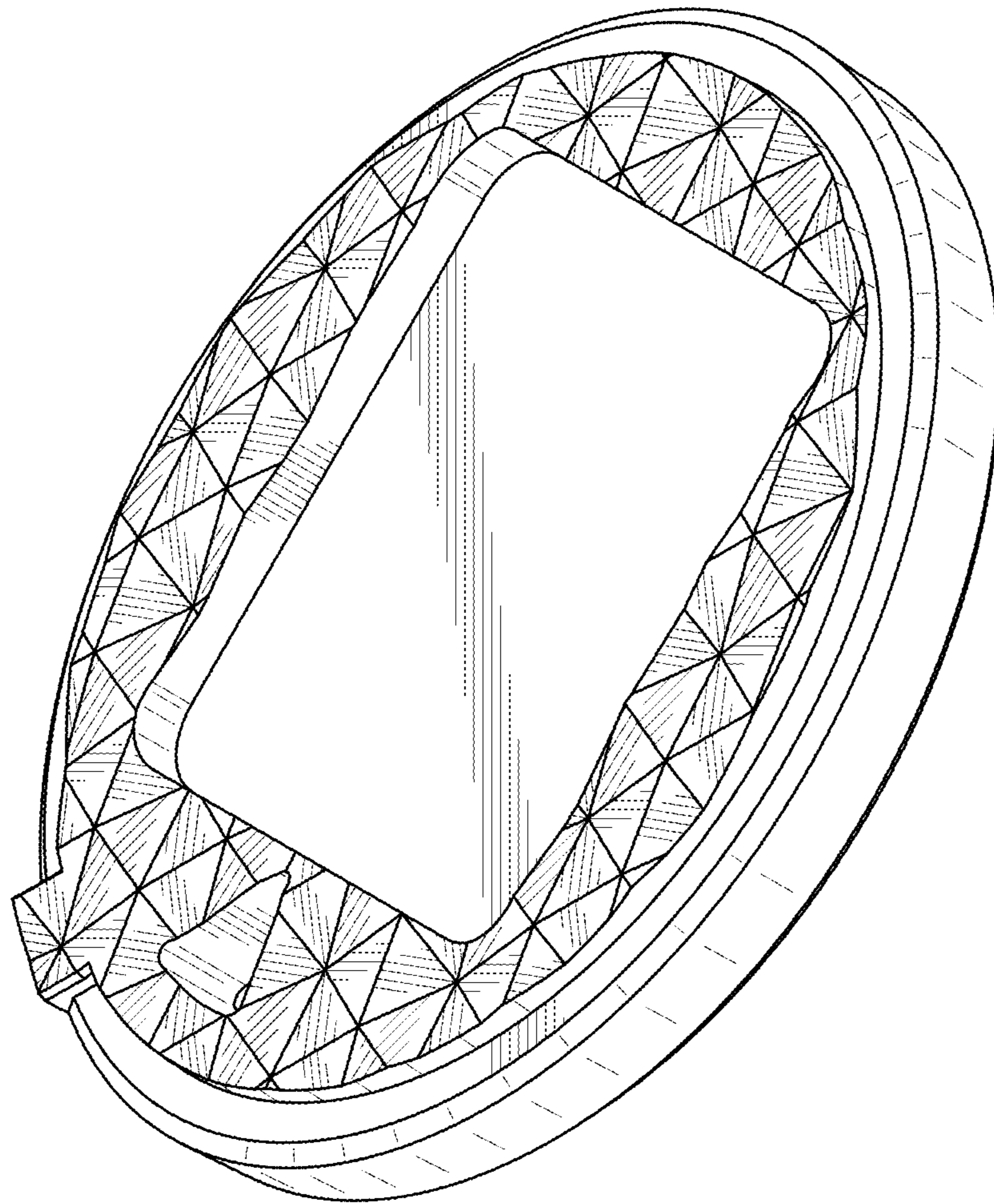


FIG. 2

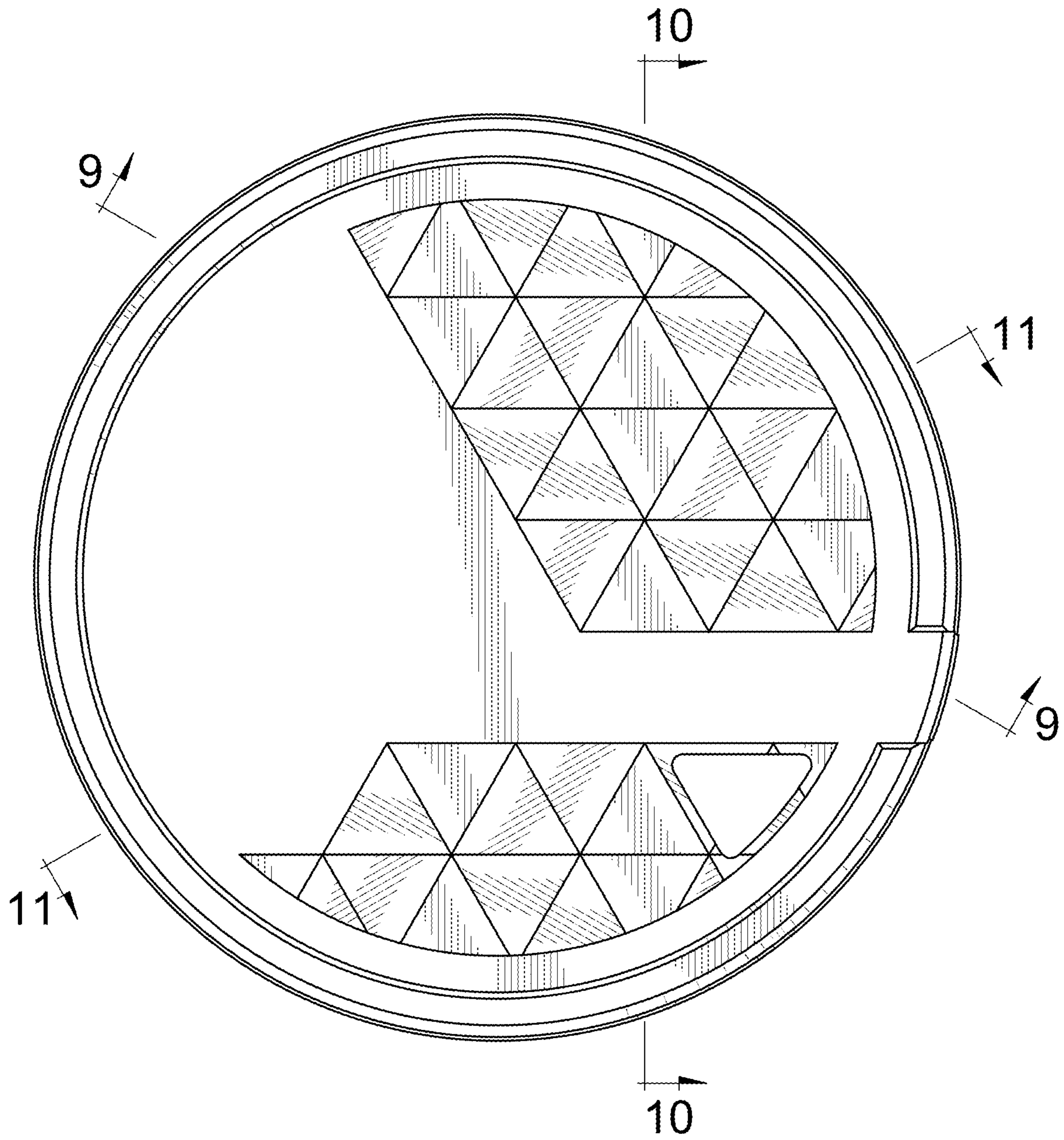


FIG. 3

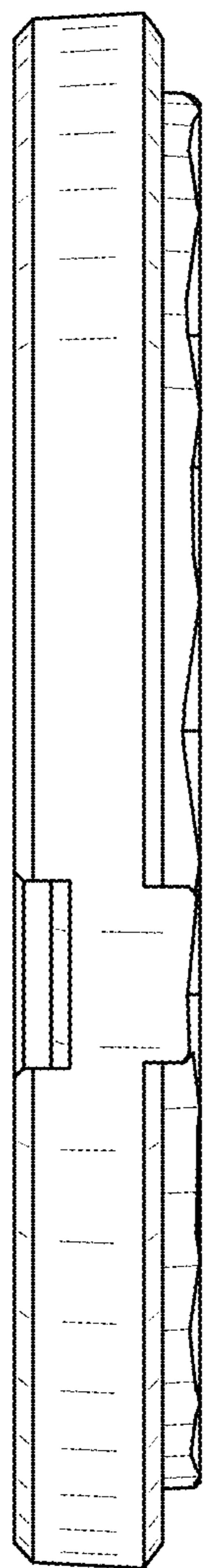


FIG. 4

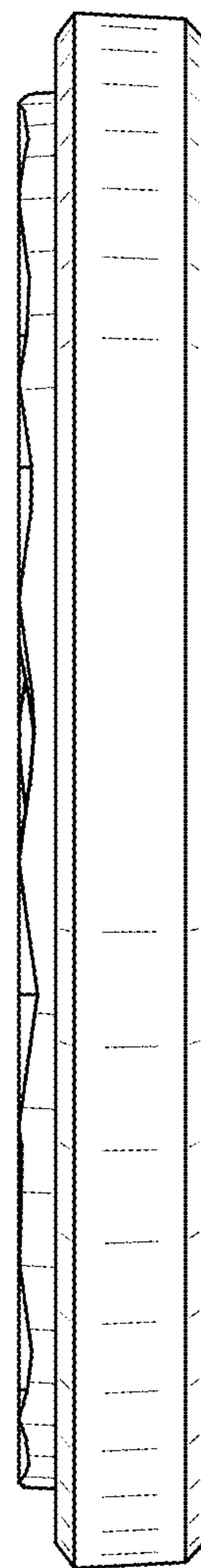


FIG. 6

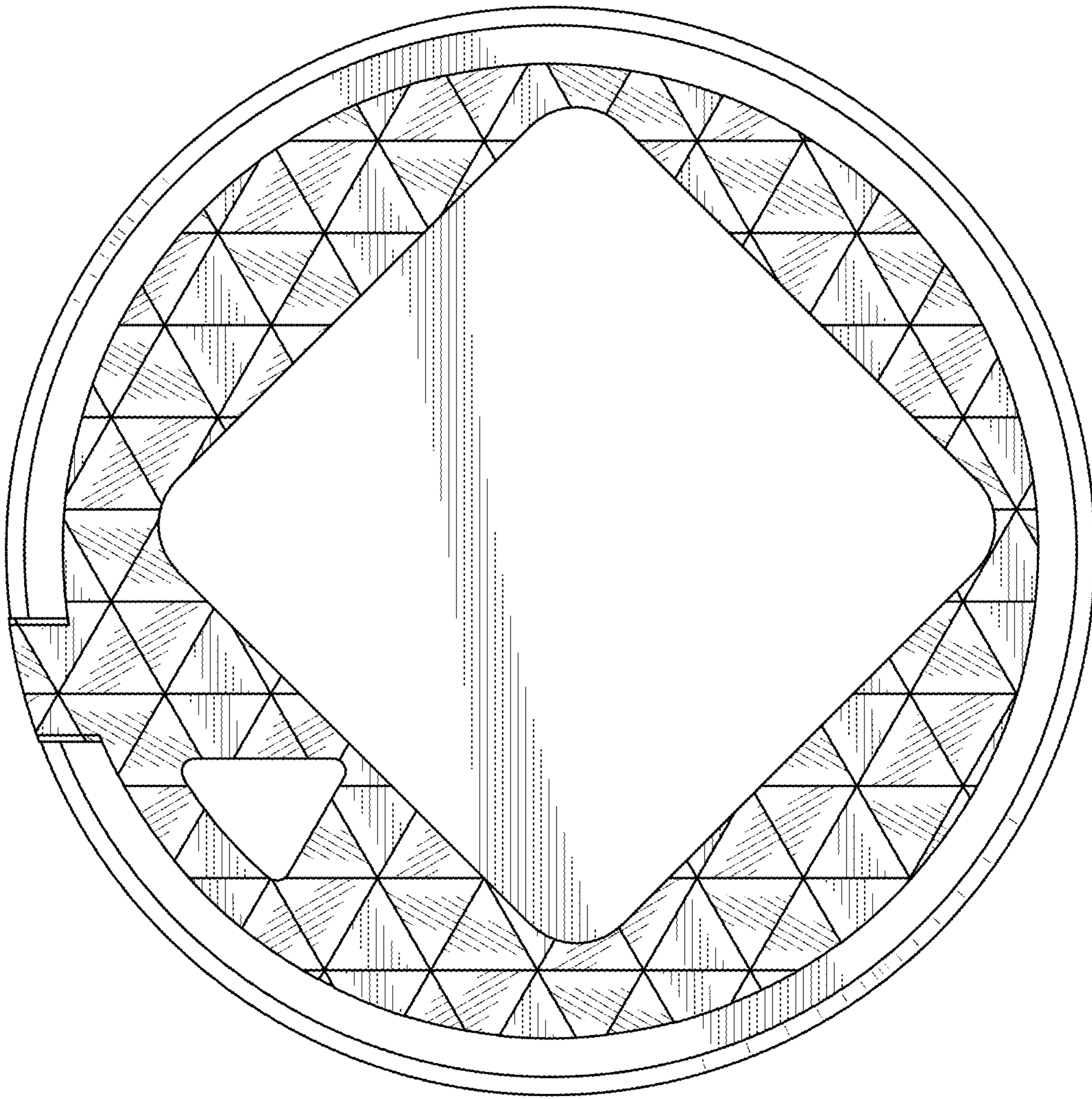


FIG. 5

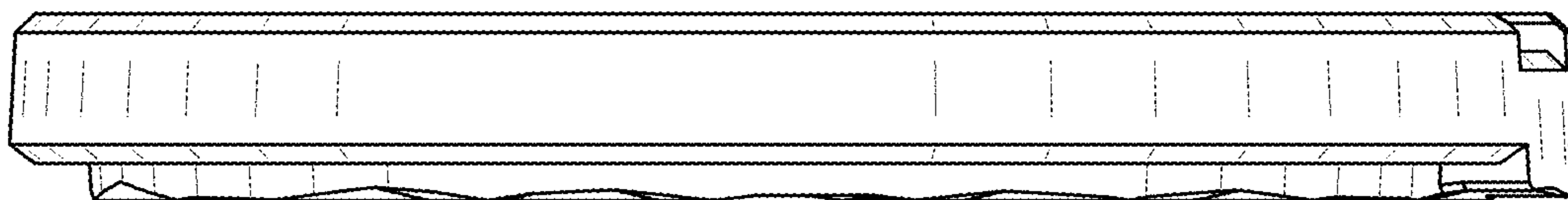


FIG. 7

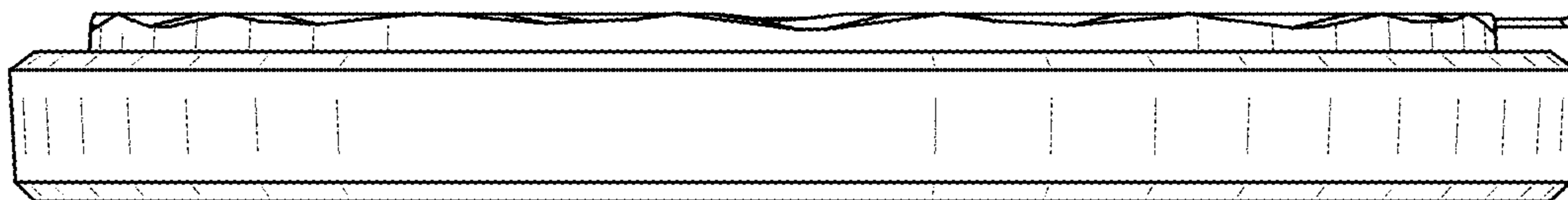


FIG. 8

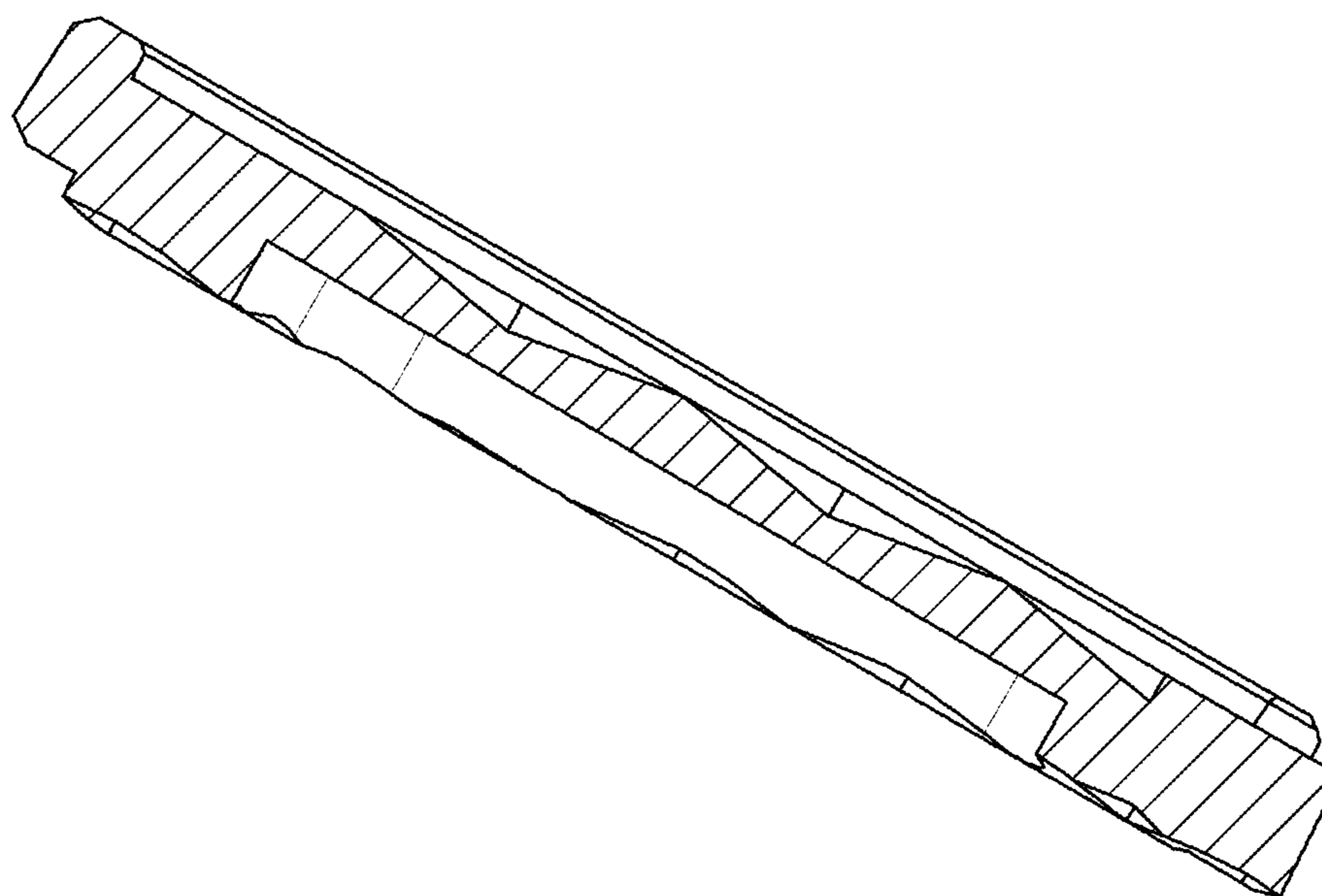


FIG. 9

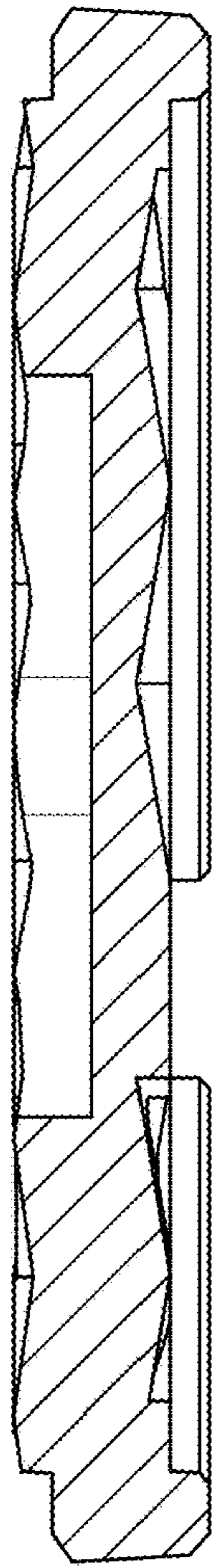


FIG. 10

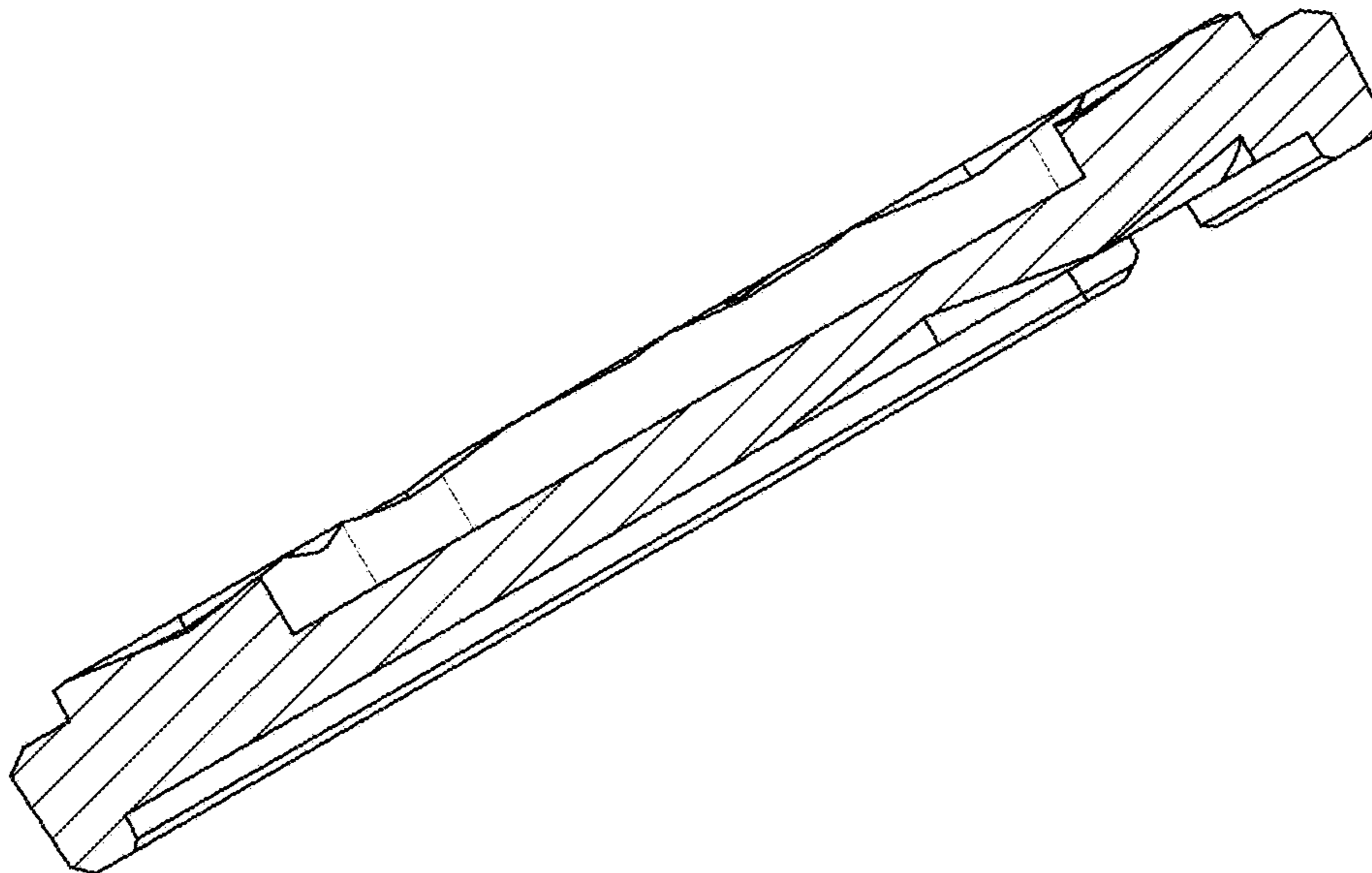


FIG. 11